12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250730006.1
Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet, and Assembly/Test site for select devices
Change Notification / Sample Request

Date: July 30, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) process.

TI requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 60 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

Changes outlined in this notification underscore our commitment to product longevity and supply continuity, as well as our continued efforts to transition to newer, more efficient manufacturing processes and technologies. Specifically, this particular notification is related to TI's multiyear transition plan for our two remaining 150-millimeter production lines (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). SFAB closure activities are expected to begin by the end of 2025. DFAB will remain open with a smaller set of 200mm technologies and GaN.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Change Management Team
SC Business Services

20250730006.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLC3702MDREP	TLC3702MDREP
TLC372MDREP	TLC372MDREP

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250730006.1	PCN Date:	July 30, 2025
Title:	Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet, and Assembly/Test site for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	October 28, 2025	Sample requests accepted until:	September 28, 2025*

***Sample requests received after September 28, 2025 will not be supported.**

Change Type:		
☒ Assembly Site	☒ Design	☐ Wafer Bump Material
☒ Assembly Process	☒ Data Sheet	☐ Wafer Bump Process
☐ Assembly Materials	☐ Part number change	☒ Wafer Fab Site
☐ Mechanical Specification	☒ Test Site	☒ Wafer Fab Materials
☒ Packing/Shipping/Labeling	☐ Test Process	☒ Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an a new Wafer Fab site for the devices listed below as well as a new Assembly/Test site, and Die revision:

Group 1 and 2

Current Fab Site			New Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
DFAB	LINCMOS	150 mm	RFAB	LBC9	300 mm

The die was also changed as a result of the process change.

Construction differences are as follows:

Group 1

	Current Site	New Site
Assembly/Test Site	FMX	**MLA**
Wire diam/type	0.96 mil Au	**0.8 mil Au**

Group 2

	Current Site	New Site
Assembly/Test Site	TAI	**MLA**
Wire diam/type	0.96 mil Au	**0.8 mil Au**

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below. For additional information, the standard data package (SDP) should be requested. The request must include the PCN# and sent to pcn_ww_admin_team@list.ti.com

The links to the revised datasheets are available in the table below:

TLC372-EP

SGLS385A – MARCH 2007 – REVISED JUNE 2025

Changes from Revision * (March 2007) to Revision A (June 2025)	Page
• Changes throughout data sheet to reflect the performance of the new design	1
• Updated the numbering format for tables, figures, and cross-references throughout the document	1

Changes from Revision A (March 2025) to Revision B (June 2025) **Page**

- Updated features 1

Changes from Revision * (July 2002) to Revision A (March 2025) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document 1
- Updated entire data sheet to reflect new die - no change to min max specifications 1

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
TLC372-EP	SGLS385	**SGLS385A**	http://www.ti.com/product/TLC372-EP
TLC3702-EP	SGLS127	**SGLS127B**	http://www.ti.com/product/TLC3702-EP

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Group 1 and 2

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DFAB	DLN	USA	Dallas
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Group 1

Current	New
Die Rev [2P]	**Die Rev [2P]**
E	**C**

Group 2

Current	New
Die Rev [2P]	**Die Rev [2P]**
B	**C**

Assembly Site Information:

Group 1

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
FMX	MEX	MEX	Aguascalientes
MLA	**MLA**	**MYS**	**KUALA LUMPUR**

Group 2

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TAI	TAI	TWN	Taipei City
MLA	**MLA**	**MYS**	**KUALA LUMPUR**

Sample product shipping label (not actual product label)

Product Affected:

Group 1

TLC372MDREP

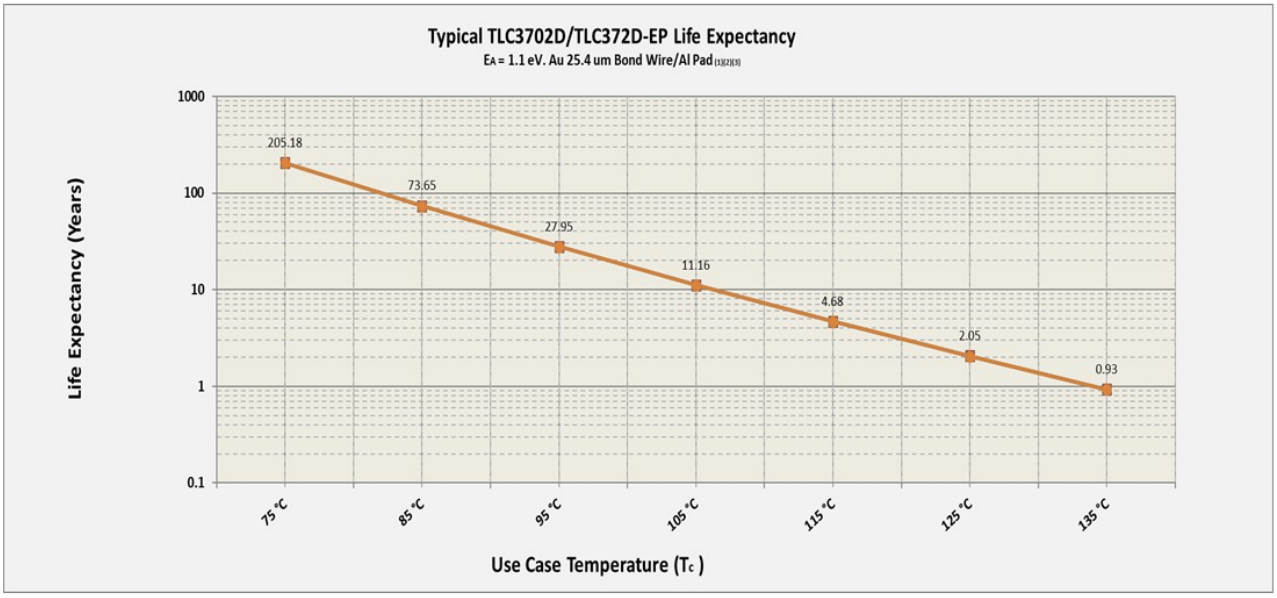
Group 2

TLC3702MDREP

For alternate parts with similar or improved performance, please visit the product page on TI.com

Enhanced Products New Device Qualification Matrix
(Note that qualification by similarity ("qualification family") per JEDEC JESD47 is allowed)

Description	Condition	Sample Size (Allowed Rejects)	Lots Required	Test Method
Electromigration	Maximum Recommended Operating Conditions	N/A	N/A	Per TI Design Rules
Wire Bond Life	Maximum Recommended Operating Conditions	N/A	N/A	Per TI Design Rules
Electrical Characterization	TI Data Sheet	15	3	N/A
Electrostatic Discharge Sensitivity	HBM	3 units/voltage	N/A	EIA/JESD22-A114 or ANSI/ESDA/JEDEC JS-001
	CDM			EIA/JESD22-C101 or ANSI/ESDA/JEDEC JS-002
Latch-up	Per Technology	3(0)	1	EIA/JESD78
Physical Dimensions	TI Data Sheet	5(0)	1	EIA/JESD22- B100
Thermal Impedance	Theta-JA on board	Per Pin-Package	N/A	EIA/JESD51
Bias Life Test	125°C/1000 hours or equivalent	45(0)	3	JESD22-A108*
Biased HAST	130°C/85%/96 hours	77(0)	3	JESD22-A110*
Extended Biased HAST**	130°C/85%/250 hours	77(-)	1	JESD22-A110*
Unbiased HAST	130°C/85%/96 hours	77(0)	3	JESD22-A.118*
Temperature Cycle	-65°C to +150°C non-biased for 500 cycles	77(0)	3	JESD22-A104*
Solder Heat	260°C for 10 seconds	22(0)	1	JESD22-B106
Resistance to Solvents	Ink symbol only	12(0)	1	JESD22-B107
Solderability	Bake Preconditioning	22(0)	1	ANSI/J-STD-002
Flammability	Method A / Method B	5(0)	1	UL94
Bond Shear	Per wire size	5 units x 30(0) bonds	3	JESD22-B116
Bond Pull Strength	Per wire size	5 units x 30(0) bonds	3	ASTM F-459 or TM2011
Die Shear	Per die size	5(0)	3	TM 2019
High Temp Storage	150 °C / 1,000 hours	15(0)	3	JESD22-A103*
Moisture Sensitivity	Surface Mount Only	12	1	J-STD-020*
	* Precondition performed per JEDEC Std. 22, Method A112/A113 ** For information only			



For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.